

Title (en)

SPECIFIC PROCESS FOR CLEANING ELECTRONIC COMPONENTS AND/OR CIRCUITS

Title (de)

SPEZIFISCHES VERFAHREN ZUR REINIGUNG VON ELEKTRONISCHEN BAUTEILEN UND/ODER SCHALTUNGEN

Title (fr)

PROCÉDÉ SPECIFIQUE DE NETTOYAGE DE COMPOSANTS ET/OU DE CIRCUITS ELECTRONIQUES

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Application

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Abstract (en)

[origin: WO2014191690A1] The invention relates to a device (1) for cleaning electronic components and/or circuits (6). Said cleaning device comprises a first vessel (2) containing a liquid, support means (8), a fluid injection system comprising nozzles (10) allowing the projection of jets of fluid, means allowing the jets from the nozzles (10) to sweep the surface of the components (6), and a fluid mixer (16) comprising a first inlet (161) suitable for receiving a pressurised liquid, a second inlet (162) suitable for receiving a pressurised gas, and an outlet (163) designed to supply the injection system with two-phase fluid, the first inlet (161) being coupled to the outlet (163) by means of an inner duct, the second inlet (162) being coupled to a pressurised gas supply and to an injector for injecting said gas into the inner duct.

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